INTERPACK 2020 TECHINCAL PRESENTATIONS SCHEDULE (AVAILABLE ON DEMAND – OCTOBER 27-JANUARY 24, 2021)

Submission Code	ASME Paper No.	Last Name	First Name	Presenter	Paper Type	Paper Title	Session
55046	InterPack-2577	AbdelAziz	Mostafa	Mostafa AbdelAziz	Technical Presentation Only	Real-Time Viewing of Electromigration in Cross-Sectioned Flip Chip Solder Joints	Flexible and Wearable Electronics
55107	InterPack-2625	Abdelmessih	Amanie	Amanie Abdelmessih	Technical Paper Publication	Personal Heating/cooling System Using Peltier Effect	Multiscale Energy Transport, Conversion, and Storage
55127	InterPack-2653	Al Ahsan	Mohammad	Mohammad Al Ahsan	Technical Presentation Only	Evolution of Mechanical Properties of Sac305 Lead Free Solder Materials Subjected to Different Thermal Cycling Profiles	Autonomous, Hybrid, and Electric Vehicles
55217	InterPack-2745	Alsaati	Albraa A.	Albraa A. Alsaati	Technical Presentation Only	Toward Embedded Immersion Cooling for Thermal Management in Heterogeneous Packaging	Heterogeneous Integration
55024	InterPack-2542	Amalfi	Raffaele Luca	Raffaele Luca Amalfi	Technical Paper Publication	Ultra-Compact Microscale Heat Exchanger for Advanced Thermal Management in Datacenters	Servers of the Future, Edge and Cloud Computing
55006	InterPack-2529	Baraya	Kalind	Kalind Baraya	Technical Presentation Only	Compact Modeling of Vapor Chambers Using Effective Anisotropic Properties	Servers of the Future, Edge and Cloud Computing
55021	InterPack-2538	Bongarala	Manohar	Manohar Bongarala	Technical Presentation Only	Experimental Demonstration of the Coupling Between Wicking and Evaporation During Critical Heat Flux on Structured Surfaces	Power Electronics
55056	InterPack-2576	Carlton	Hayden	Hayden Carlton	Technical Paper Publication	Multifunctional Magnetic Nanocomposite Encapsulant for Emi Shielding in Power Electronics	Power Electronics
55209	InterPack-2739	Chalise	Divya	Divya Chalise	Technical Presentation Only	Heat of Mixing in Nmc523 Cathode During Fast Charge/discharge	Multiscale Energy Transport, Conversion, and Storage
54972	InterPack-2547	Chen	Ching Chia	Ching Chia Chen	Technical Paper Publication	High Performance Computing Package With Chip Module on Substrate Solutions	Servers of the Future, Edge and Cloud Computing
54980	InterPack-2506	Chen	Li	Li Chen	Technical Presentation Only	An Electricity Flow Model for Enhancing u.s. State-Based Life Cycle Carbon Emission Factor Predictions	Multiscale Energy Transport, Conversion, and Storage
55094	InterPack-2612	Chen	Changqing	Changqing Chen	Technical Presentation Only	Novel Strategies to Develop Algan-Based Deep-Uv Led and Laser	Optics and Photonics
55168	InterPack-2696	Chen	Jun	Jun Chen	Technical Presentation Only	Temperature Dependent Piezoresistive Coefficients of 4h Silicon Carbide	Power Electronics

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55003	InterPack-2525	Davila-Frias	Alex	Alex Davila-Frias	Technical Paper Publication	Design of Accelerated Degradation Test Method and Failure Analysis of Flexible Hybrid Electronic Devices	Flexible and Wearable Electronics
55231	InterPack-2765	Deshpande	Abhishek	Abhishek Deshpande	Technical Presentation Only	Effect of Tensile vs Shear Loading on the Stress-Strain Response of Grain-Scale Solder Interconnects	Heterogeneous Integration
55129	InterPack-2655	Fahim	Abdullah	Abdullah Fahim	Technical Paper Publication	Creep Behavior of Various Materials Within Pbga Packages Subjected to Thermal Cycling Loading	Autonomous, Hybrid, and Electric Vehicles
55065	InterPack-2668	Farzinazar	Shiva	Shiva Farzinazar	Technical Presentation Only	3d Architected Packaging Structures for Thermal Management	Multiscale Energy Transport, Conversion, and Storage
54976	InterPack-2555	Gadhiya	Ghanshyam	Ghanshyam Gadhiya	Technical Paper Publication	The Systematic Study of Fan-Out Wafer Warpage Using Analytical, Numerical and Experimental Methods	Autonomous, Hybrid, and Electric Vehicles
55053	InterPack-2565	Gresham-Chisolm	Damon	Damon Gresham-Chisoholm and Sonya T. Smith	Technical Paper Publication	Thermal Analysis of Wavy Thermal Management System With Phase Change Composite and Pyrolytic Graphite Sheet for Cylindrical Lithium-Ion Battery Module	Power Electronics
55162	InterPack-2690	Haq	Mohammad Ashraful	Mohammad Ashraful Haq	Technical Paper Publication	Determination of Anand Parameters From Creep Testing of Sac305 Solder Joints	Autonomous, Hybrid, and Electric Vehicles
55165	InterPack-2693	Hasan	Sm Kamrul	SM Kamrul Hasan	Technical Paper Publication	Evaluation of the Creep Response of Lead-Free Solder Materials Subjected to Thermal Cycling	Autonomous, Hybrid, and Electric Vehicles
55163	InterPack-2691	Hassan	Km Rafidh	KM Rafidh Hassan	Technical Paper Publication	Time-Lapse Imagery and Quantitative Analysis of Microstructural Evolution of Sac305 Bga Joints During Extreme High Temperature Aging	Power Electronics
55012	InterPack-2533	Hazra	Sougata	Sougata Hazra	Technical Paper Publication	Characterization and Prevention of Metal Overflow in Au-Sn Eutectic Chip Bonding for Electronic Packaging Applications	Heterogeneous Integration
55028	InterPack-2640	Hazra	Sougata	Sougata Hazra	Technical Paper Publication	Enhancement of Capillary Wicking Performance in Micro-Pillar Forest Geometry by Laser Induced Roughness	Heterogeneous Integration
55099	InterPack-2627	Hoang	Cong Hiep	Cong Hiep Hoang	Technical Paper Publication	Liquid Cooling Utilizing a Hybrid Micro-Channel/multi-Jet Heat Sink: A Component Level Study of Commercial Product	Servers of the Future, Edge and Cloud Computing

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Submission Code	ASME Paper No.	Last Name	First Name	Presenter	Paper Type	Paper Title	Session
55008	InterPack-2557	Hoe	Alison	Alison Hoe	Technical Presentation Only	Experimental Observations on the Dynamic Response of Phase Change Materials	Multiscale Energy Transport, Conversion, and Storage
55054	InterPack-2567	Hollowell	Andrew	Matthew B. Jordan	Technical Presentation Only	High Density Microbump Development for Multi-Project Wafer (Mpw) Die	Heterogeneous Integration
55164	InterPack-2692	Hoque	Mohd Aminul	Mohammad Aminul Hoque	Technical Paper Publication	Study of Lead Free Solder Joints Subjected to Isothermal Mechanical Shear Cycling	Autonomous, Hybrid, and Electric Vehicles
55081	InterPack-2598	Huitink	David	Mahsa Montazeri	Technical Paper Publication	Development of a Novel Test Setup to Study the Combined Effects of Electromigration and Thermomechanical Stress in Solder Interconnects	Heterogeneous Integration
55083	InterPack-2599	Huitink	David	David Huitink	Technical Presentation Only	Warpage and Stress Reduction Using Auxetic Featrues	Heterogeneous Integration
55005	InterPack-2528	Hung	Chupao (otis)	Chu Pao (Otis) Hung	Technical Paper Publication	Fan-Out Mcm Solutions Study for Heterogeneous Integration on Intelligent Computing Application	Heterogeneous Integration
55043	InterPack-2570	Ishitani	Yoshihiro	Yoshihiro Ishitani	Technical Paper Publication	Local Heat Energy Transport Analyses in Gainn/gan Heterostructure by Microscopic Raman Imaging Employing Simultaneous Irradiation of Two Laser Beams	Optics and Photonics
55004	InterPack-2527	Jennings, Jr.	Darryl	Darryl Jennings, Jr. & Sonya T. Smith	Technical Paper Publication	Comparative Study of Effective Cooling in Microchannel Heat Sinks (Mchs) With Nanofluid and Hydrophobic Nanostructures Using Computational Fluid Dynamics	Power Electronics
55075	InterPack-2591	Kailkhura	Gargi	Gargi Kailkhura	Technical Paper Publication	Experimental Study of a Set of Integrated Cross-Media Heat Exchangers (Icmhxs) for Liquid Cooling in Desktop Computers	Servers of the Future, Edge and Cloud Computing
54975	InterPack-2556	Kato	Mitsuaki	Mitsuaki Kato	Technical Paper Publication	Electromigration Analysis of Solder Joints for Power Modules Using an Electrical-Thermal-Stress Coupled Model	Power Electronics
55196	InterPack-2725	Kingston	Todd	Todd Kingston	Technical Presentation Only	Time-Resolved Characterization of Microchannel Flow Boiling During Transient Heating	Servers of the Future, Edge and Cloud Computing
55071	InterPack-2589	Krone	Alexis	Alexis Krone	Technical Paper Publication	Degradation of Gallium Nitride-Based Hall Effect Sensors in High Temperature Environments	Power Electronics
55122	InterPack-2647	Lall	Pradeep	Hyesoo Jang	Technical Paper Publication	Twist Reliability Assessment of Flexible Battery In Wearable Applications	Autonomous, Hybrid, and Electric Vehicles

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Submission Code	ASME Paper No.	Last Name	First Name	Presenter	Paper Type	Paper Title	Session
55132	InterPack-2658	Lall	Pradeep	Vikas Yadav	Technical Paper Publication	Evolution of Sac Leadfree Alloys at High Strain Rate at Low Operating Temperatures	Autonomous, Hybrid, and Electric Vehicles
55134	InterPack-2659	Lall	Pradeep	Mrinmoy Saha	Technical Paper Publication	High Strain Rate Low Temperature Properties for Sac-R After Exposure to Isothermal Aging	Autonomous, Hybrid, and Electric Vehicles
55135	InterPack-2660	Lall	Pradeep	Vishal Mehta	Technical Paper Publication	High Strain Rate Mechanical Properties of Sac-Q Between -65c and +200c After Exposure to Isothermal Aging	Autonomous, Hybrid, and Electric Vehicles
55148	InterPack-2675	Lall	Pradeep	Madhu Kasturi	Technical Paper Publication	Correlation of Microstructural Evolution With the Dynamic-Mechanical Viscoelastic Properties of Underfill Under Sustained High Temperature Operation	Autonomous, Hybrid, and Electric Vehicles
55149	InterPack-2676	Lall	Pradeep	Padmanava Choudhury	Technical Paper Publication	Fe Modelling and Experimental Study of Crack Propagation at the Pcb/underfill Interface Due to Thermal Aging	Autonomous, Hybrid, and Electric Vehicles
55150	InterPack-2677	Lall	Pradeep	Yunli Zhang	Technical Paper Publication	Degradation Mechanisms of Underfills Subjected to Isothermal Long-Term Aging From 150c to 200c	Autonomous, Hybrid, and Electric Vehicles
55152	InterPack-2678	Lall	Pradeep	Sungmo Jung	Technical Paper Publication	Reliability Assessment of Cu-Al Wb Under High Temperature and High Voltage Bias Application	Autonomous, Hybrid, and Electric Vehicles
55118	InterPack-2644	Lall	Pradeep	Hyesoo Jang	Technical Paper Publication	Reliability of Flexible Wearable Band With Printed Sensors for Vital Sign Acquisition	Flexible and Wearable Electronics
55139	InterPack-2664	Lall	Pradeep	Jinesh Narangaparambil	Technical Paper Publication	Development of Process-Recipe for Multi-Layer Circuitry Printing With Z-Axis Interconnects Using Aerosol-Jet Nanoparticle Ink	Flexible and Wearable Electronics
55154	InterPack-2680	Lall	Pradeep	Kartik Goyal	Technical Paper Publication	Process-Consistency in Additively Printed Multi-Layer Substrates With Offset Vias Using Aerosol Jet Technology	Flexible and Wearable Electronics
55136	InterPack-2661	Lall	Pradeep	Ved Soni	Technical Paper Publication	Effect of Flex-to-Install and Dynamic Folding on Li-Ion Battery Performance Degradation Subjected to Varying Orientations, Folding Speeds, Depths of Charge and C-Rates	Multiscale Energy Transport, Conversion, and Storage
55123	InterPack-2648	Lall	Pradeep	Aathi Raja Ram Pandurangan	Technical Paper Publication	Non-Perpendicular Orientation High-G Impact Reliability of Electronics Potted Assemblies	Autonomous, Hybrid, and Electric Vehicles
55153	InterPack-2679	Lall	Pradeep	Tony Thomas	Technical Paper Publication	Feature Vector Identification and Prognostics of Sac305 Pcb's for Varying Conditions of Temperature and Vibration Loads	Servers of the Future, Edge and Cloud Computing

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Submission Code	ASME Paper No.	Last Name	First Name	Presenter	Paper Type	Paper Title	Session
55195	InterPack-2724	Lan	Wei	Wei Lan	Technical Presentation Only	Transient Heat Transfer Model for Real-Time Temperature Prediction of Downhole Electronics	Power Electronics
55151	InterPack-2681	Li	Mo	Mo Li	Technical Presentation Only	Recent Advances in Photonic Physical Unclonable Functions for Authentication and Anticounterfeiting	Optics and Photonics
55033	InterPack-2619	Lim	Jungyun	Jungyun Lim	Technical Presentation Only	Lateral Thermoelectric Cooling by Anisotropic Composites for Hot Spot Thermal Management	Multiscale Energy Transport, Conversion, and Storage
55051	InterPack-2563	Lundh	James Spencer	James Spencer Lundh	Technical Presentation Only	2d Material Assisted Raman Thermometry for Thermal Characterization of Ultra-Wide Bandgap Electronics	Power Electronics
55044	InterPack-2564	Mandel	Raphael	Fabio Battaglia	Technical Paper Publication	A Porous Medium Approach for Single-Phase Flow and Heat Transfer Modeling in Manifold Microchannel Heat Exchangers	Multiscale Energy Transport, Conversion, and Storage
55086	InterPack-2605	Miorini	Rinaldo	Rinaldo Miorini	Technical Paper Publication	Thermal Model of the Package Integrated Cyclone Cooler (Picco) - Achieving High Thermal Energy Storage Capability and Conductance Using Swirled Two-Phase Flow	Power Electronics
55063	InterPack-2581	Mohammad Nafis	Bakhtiyar	Bakhtiyar Mohammad Nafis	Technical Paper Publication	System and Component Level Risk Assessment for SiC MOSFET Based Inverter for Traction Application	Power Electronics
55166	InterPack-2694	Mondal	Debabrata	Debabrata Mondal	Technical Paper Publication	Deformation Behavior Sac305 Solder Joints With Multiple Grains	Autonomous, Hybrid, and Electric Vehicles
55133	InterPack-2662	Murthy	Prajwal	Prajwal Murthy	Technical Paper Publication	Numerical Analysis of Oil Immersion Cooling of a Server Using Mineral Oil and Al2o3 Nanofluid	Servers of the Future, Edge and Cloud Computing
54984	InterPack-2531	Negita	Daiki	Daiki Negita	Technical Presentation Only	Critical Heat Flux Improvement of Two-Phase Immersion Cooling by Controlling Breathing Phenomenon	Power Electronics
55078	InterPack-2595	Niazmand	Amirreza	Amirreza Niazmand	Technical Paper Publication	Cfd Simulation of Two-Phase Immersion Cooling Using Fc-72 Dielectric Fluid	Power Electronics
54979	InterPack-2631	Nishi	Koji	Koji Nishi	Technical Paper Publication	Investigation Regarding Thermal Resistance of Surface Mount Type Discrete Power Semiconductor Package	Power Electronics
55058	InterPack-2572	Ohkawa	Kazuhiro	Kazuhiro Ohkawa	Technical Presentation Only	Red Ingan-Leds Using Strain-Compensated Quantum Well Structures	Optics and Photonics

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55031	InterPack-2569	Oksuz	Enes Abdulhakim	Enes Abdülhakim Öksüz	Technical Paper Publication	Frosting Effects on Different Fin Types	Multiscale Energy Transport, Conversion, and Storage
55080	InterPack-2596	Olatunji	Tumininu	Tumininu Olatunji	Technical Paper Publication	Additive Fabricated Compliant Interconnects: Design, Fabrication & Reliability Effects	Power Electronics
55095	InterPack-2614	Otto	Alexander	Alexander Otto	Technical Paper Publication	Phm Features for Large Circuit Boards and Power Devices for Electric Drivetrain Applications	Autonomous, Hybrid, and Electric Vehicles
55014	InterPack-2534	Ozguc	Serdar	Serdar Ozguc	Technical Presentation Only	Topology Optimization of Microchannel Heat Sinks Using a Homogenization Approach	Power Electronics
55104	InterPack-2622	Pan	Junyou	Junyou Pan	Technical Presentation Only	Organic Semiconductors for Next Generation Display	Optics and Photonics
55201	InterPack-2733	Poliks	Mark	Mark D. Poliks	Technical Presentation Only	Assessing the Reliability of Aerosol Jet Printed Nano-Particle Traces on Flex Under Realistic Use Conditions	Flexible and Wearable Electronics
55106	InterPack-2624	Qian	Lei	Lei Qian	Technical Presentation Only	High Efficiency and Stability of Ink-Jet Printed Quantum Dot Light Emitting Diodes	Optics and Photonics
55041	InterPack-2615	Ren	Zongqing	Zongqing Ren	Technical Presentation Only	Holey Silicon-Based Monolithic Thermal Cloak	Multiscale Energy Transport, Conversion, and Storage
55077	InterPack-2601	Roy	Souvik	Souvik Roy	Technical Presentation Only	Polymer Composites for Thermal Energy Storage	Multiscale Energy Transport, Conversion, and Storage
54994	InterPack-2516	Sahu	Raj	Raj Sahu	Technical Paper Publication	Liquid-Cooled Heat Sink Optimization for Thermal Imbalance Mitigation in Wide-Bandgap Power Modules	Power Electronics
55074	InterPack-2590	Saini	Satyam	Satyam Saini	Technical Paper Publication	Cfd Investigation of the Distribution and Dispersion of Airborne Particulate Contaminants Inside Data Center Hardware	Servers of the Future, Edge and Cloud Computing
59127	InterPack-2769	Saini	Satyam	Satyam Saini	Technical Presentation Only	Accelerated Thermal Degradation of Printed Circuit Board, Passive Components and Fiber Optic Cables for Single-Phase Immersion Cooled Data Centers	Servers of the Future, Edge and Cloud Computing
55039	InterPack-2553	Salamon	Todd	Todd Salamon	Technical Paper Publication	Partitioned Heat Sinks for Improved Natural Convection	Servers of the Future, Edge and Cloud Computing

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Submission Code	ASME Paper No.	Last Name	First Name	Presenter	Paper Type	Paper Title	Session
55037	InterPack-2551	Salamon	Todd	Todd Salamon	Technical Presentation Only	Die-Level Thermal Modeling of a Silicon Germanium (Sige) Bicmos Radio Frequency Integrated Circuit (Rfic) for Wireless Communications	Heterogeneous Integration
55015	InterPack-2550	Sequeira	Sebastien	Sebastien Sequeira	Technical Paper Publication	Validation and Parametric Investigations Using a Lumped Thermal Parameter Model of an Internal Permanent Magnet Motor	Autonomous, Hybrid, and Electric Vehicles
55076	InterPack-2592	Shahi	Pardeep	Pardeep Shahi	Technical Paper Publication	CFD Analysis on Liquid Cooled Cold Plate Using Copper Nanoparticles	Servers of the Future, Edge and Cloud Computing
55142	InterPack-2670	Shao	Shuai	Shuai Shao	Technical Paper Publication	Evaluation of Single Phase Immersion Cooling System for High Performance Server Using Dielectric Coolants	Servers of the Future, Edge and Cloud Computing
55125	InterPack-2684	Shen	Chao	Chao Shen	Technical Presentation Only	Laser-Based Visible Light Communication Devices and Systems for Underwater Iot	Optics and Photonics
55067	InterPack-2580	Shoemaker	Daniel	Daniel Shoemaker	Technical Presentation Only	Enhancement of the Electrical and Thermal Performance of Gan Hemts Using a Novel Resistive Field Plate Structure	Power Electronics
55047	InterPack-2560	Shoemaker	Daniel	Bikramjit Chatterjee	Technical Presentation Only	Nanoscale Electro-Thermal Interactions in Algan/gan High Electron Mobility Transistors	Power Electronics
55032	InterPack-2562	Singh	Ayushman	Ayushman Singh	Technical Paper Publication	Effective Thermal Conductivity of Phase Change Material-Based Composites for Electronic Cooling	Multiscale Energy Transport, Conversion, and Storage
55091	InterPack-2609	Soleymani	Azita	Yes	Technical Paper Publication	Real Time Prediction of Temperature and Heat Generation Rate of Li-Ion Battery Packs in Ev Vehicles	Autonomous, Hybrid, and Electric Vehicles
55048	InterPack-2561	Song	Yiwen	Yiwen Song	Technical Presentation Only	Thermal Characterization of Gallium Oxide Heterostructures	Power Electronics
55198	InterPack-2729	Stewart	Benjamin	Benjamin Stewart	Technical Presentation Only	Biaxial Inflation Stretch Test for Printed Flexible Electronics	Flexible and Wearable Electronics
54982	InterPack-2507	Su	Po Yuan(james)	Po Yuan (James) Su	Technical Paper Publication	Material Impact With Package Solution for 5g Rf Application	Heterogeneous Integration
55098	InterPack-2617	Sun	Haiding	Haiding Sun	Technical Presentation Only	Algan - Based Optoelectronics: Deep Ultraviolet Light Emitting Diodes and Solar-Blind Photodetectors	Optics and Photonics
55035	InterPack-2549	Syu	Ji-Yuan	Ji-Yuan Syu	Technical Presentation Only	Innovative High Density Power Module for E-Scooter Motor Using a High Performance Insulated Metal Substrate	Power Electronics

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55023	InterPack-2541	Thome	John Richard	John Richard Thome	Technical Paper Publication	Experimental Validation and Design Simulations of a Passive Two-Phase Cooling System for Datacenters	Servers of the Future, Edge and Cloud Computing
55062	InterPack-2638	Tomko	John	John A. Tomko	Technical Presentation Only	Long-Lived Modulation of Plasmonic Absorption by Ballistic Thermal Injection	Optics and Photonics
55069	InterPack-2585	Tompkins	Joshua	Joshua Tompkins	Technical Presentation Only	An Additive Manufacturing Approach to Air Flow Inversion for Enhanced Thermal Management and Reliability	Power Electronics
55090	InterPack-2611	Wang	Dan	Dan Wang	Technical Presentation Only	Process Intensification for Scalable Production of Optical Functional Nanomaterials and Their Applications	Optics and Photonics
55146	InterPack-2673	Wang	Lai	Lai Wang	Technical Presentation Only	A High-Speed Light-Emitting Diode With Bandwidth > 1ghz Based on Ingan/gan Quantum Dots Active Region	Optics and Photonics
55018	InterPack-2566	Wei	Tiwei	Tiwei Wei	Technical Presentation Only	Parametric Cfd Study of Large Footprint (24 X 24mm2) Silicon-Based Embedded Microchannel-3d Manifold Coolers	Power Electronics
54977	InterPack-2504	Wemhoff	Aaron	Aaron Wemhoff	Technical Presentation Only	Thermo-Economic Assessment of Recovering Waste Heat From Data Centers Through an Organic Rankine Cycle	Servers of the Future, Edge and Cloud Computing
55011	InterPack-2532	White	Andrew	Andrew Scott White	Technical Paper Publication	Performance Analysis of Heat Sinks Designed for Additive Manufacturing	Power Electronics
55079	InterPack-2597	Whitt	Reece	Reece Whitt	Technical Presentation Only	Durability of Non-Metallic Additive Manufactured Jet Impingement Manifolds in Elevated Temperature Power Electronics Thermal Management	Power Electronics
55082	InterPack-2603	Wu	Qianying	Qianying Wu	Technical Paper Publication	Design and Fabrication of Graded Copper Inverse Opals (G-Cios) for Capillary-Fed Boiling in High Heat Flux Cooling Applications	Power Electronics
55167	InterPack-2695	Wu	Jing	Jing Wu	Technical Paper Publication	Investigation and Comparison of Aging Effects in Sac305 and Doped Sac+x Solders Exposed to Isothermal Aging	Autonomous, Hybrid, and Electric Vehicles
55145	InterPack-2672	Wu	Feng	Feng Wu	Technical Presentation Only	High Performance Photovoltaic Detectors Based on Van Der Waals Heterojunctions	Optics and Photonics
55143	InterPack-2669	Zhao	Yuji	Yuji Zhao	Technical Presentation Only	Gallium Oxide as an Exciting New Optical Material for the Ultraviolet and Visible Integrated Photonics Applications	Optics and Photonics

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55193	InterPack-2722	Zhou	Shuling	Shuling Zhou	Technical Presentation Only	Improved Optical Consistency of Phosphor and Quantum Dots Converted White Light-Emitting Diodes	Optics and Photonics
55147	InterPack-2674	Zhou	Shengjun	Shengjun Zhou and Xiaoyu Zhao	Technical Presentation Only	Recent Advances in High-Efficiency Nitride-Based Blue/green/ultraviolet Light-Emitting Diodes	Optics and Photonics